

# 深圳市华显美科技有限公司

## AMOLED

### Product Specification

Model Name:    E544-HC01

Description:    5.44" FHD AMOLED

Doc. Version:    01

Customer:

- Approved for Preliminary Specification
- Approved for Final Specification
- Approved for Final Specification & Sample

此规格只能符合 AMOLED 单体规格，不含整机规格

Prepared by	Checked by	Approved by

Customer's Approval



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## 1 Scope

This Specification defines AMOLED manufactured by Voluntary Electron. In the case of any unspecified item, it may require both Voluntary Electron and the party designs this module into its product to work out a solution.

## 2 Features

### 2.1 Product Applications

mobile phone, portable GPS, handheld game console...

### 2.2 Product Features

2.2.1 Display color: 16.7M (RGB x 8bits)

2.2.2 Display format: 5.44" FHD(1080RGBx1920)

2.2.3 Pixel arrangement: Rendering

2.2.4 Interface: MIPI 4 lanes

2.2.5 Driver IC: RM67199( Raydium )

2.2.6 Touch IC: GT1151

2.2.7 Touch screen: On-Cell

2.2.8 Polarizer: Hard Coating Polarizer

## 3 Mechanical Specifications

Item	Specification	unit
Dimension outline	69.74*126.60*0.84	mm
Resolution	1080 RGB x 1920 ( Rendering )	dots
Active area	67.82 x 120.58	mm
Diagonal size	5.44	inch
Pixel pitch	31.40*62.80	μm
Glass thickness (LTPS/encapsulation glass)	0.20 / 0.30	mm
Weight	( TBD )	g

## 4 Maximum Rating

Parameter	Symbol	Spec			Unit	Note
		Min.	Typ.	Max.		
Analog/boost power voltage	VCI	-0.3	-	5.5	V	-
I/O voltage	VDDIO	-0.3	-	5.5	V	-
Power IC Input Voltage	VBAT	-0.3	-	6	V	-
Operating temperature	Top	-20		70	°C	
Storage temperature	Tstg	-30		80	°C	
Power Consumption			2000	2300	mW	

## 5 Electrical Specifications

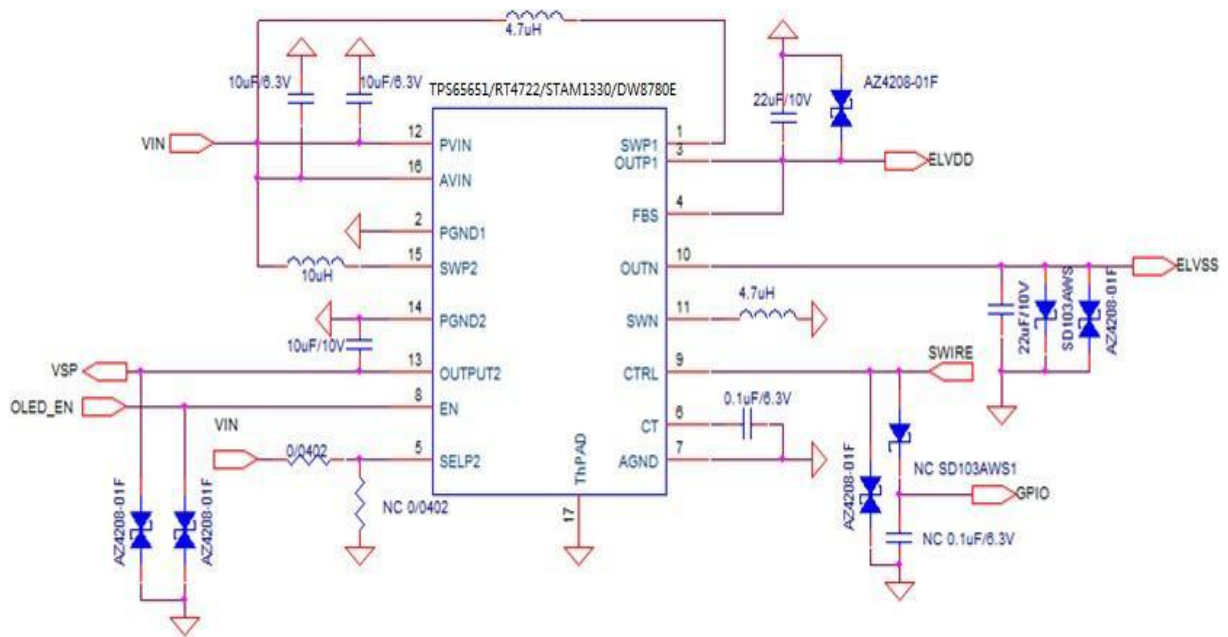
### 5.1 Electrical Characteristics

#### 5.1.1 Current Characteristic:

Item	Symbol	Min.	Typ.	Max.	Unit	Remark
Power IC Input Voltage	VBAT	2.9	-	4.5	V	Ref
Digital Power supply	VDDI	1.65	1.8	3.6	V	Ref
Analog Power supply	VCI	2.5	3.3	4.8	V	Ref
TP Power Supply voltage	AVDD	2.7	-	3.6	V	-
TP I/O Digital Voltage	Iovcc	1.65	-	3.6	V	

Mode	Symbol	Condition	Min.	Typ.	Max.	Unit	Remark
Full White @350 Nits	IVBAT	IVBAT=4V VCI=3.3V	-	460	550	mA	-
	IVCI	VDDIO=1.8V @ Full white	-	2	3	mA	-
	IVDDIO	350 nits	-	50	65	mA	-
TP Normal Operation	Iopr	AVDD=3.3V Iovcc = 1.8V		16		mA	-
TP Monitor	Imon			0.6		mA	-
TP Sleep	Islp			40		uA	-

## 5.1.2 Application circuit:



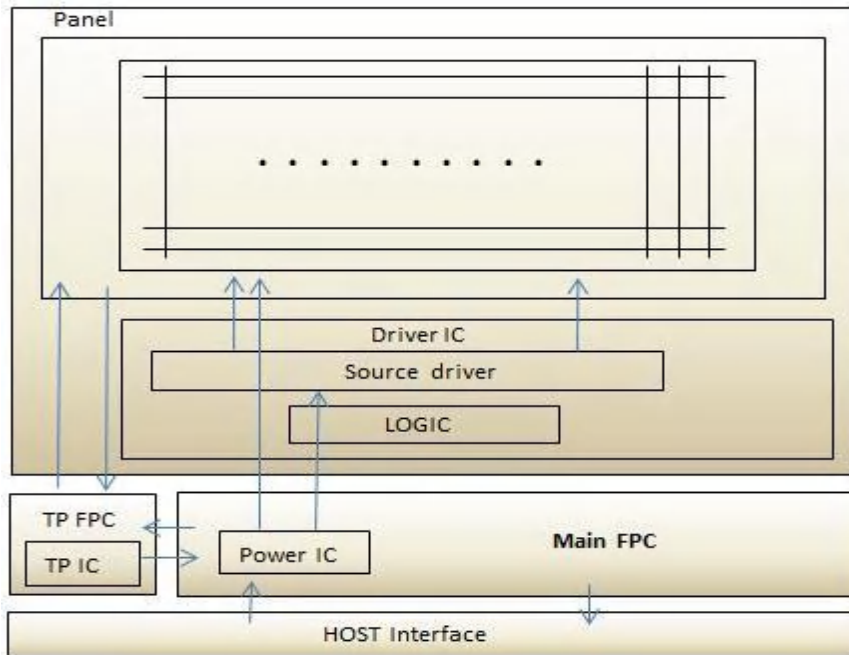
## 5.2 I/O Connection and Block Diagrams

### 5.2.1 I/O Connection

#	Pin_name	I/O	Description
1	GND	Power	The power ground
2	GND	Power	The power ground
3	GND	Power	The power ground
4	VBAT	Power	Power IC Input Voltage
5	VBAT	Power	Power IC Input Voltage
6	VBAT	Power	Power IC Input Voltage
7	VBAT	Power	Power IC Input Voltage
8	VBAT	Power	Power IC Input Voltage
9	GND	Power	The power ground
10	VPP	Power	Power supply for OTP. Leave the pin to open when not in use.
11	NC	-	No connection
12	GND	Power	The power ground
13	D3P	I	MIPI DSI data3+

14	D3N	I/O	MIPI DSI data3-
15	GND	Power	The power ground
16	D0P	I/O	MIPI DSI data0+
17	D0N	I/O	MIPI DSI data0-
18	GND	Power	The power ground
19	CLKP	I	MIPI DSI clock+
20	CLKN	I	MIPI DSI clock-
21	GND	Power	The power ground
22	D1P	I/O	MIPI DSI data1+
23	D1N	I/O	MIPI DSI data1-
24	GND	Power	The power ground
25	D2P	I/O	MIPI DSI data2+
26	D2N	I/O	MIPI DSI data2-
27	GND	Power	The power ground
28	RESX	I	This signal will reset the device and must be applied to properly initialize the chip. Active low.
29	VDDIO	Power	Driver IC digital I/O supply
30	VCI	Power	Driver IC analog supply
31	TE	O	Tear effect output
32	GND	Power	The power ground
33	TSP_AVDD	Power	TP IC digital power supply
34	TSP_DVDD	Power	TP IC digital I/O supply
35	TSP_SDA	I/O	I2C Data Input & Output
36	TSP_SCL	I/O	I2C Clock Input
37	TSP_RESET	I	External Reset, Low is Active
38	TSP_ATTN	I	Interrupt request to the host, or Wakeup request from the host.
39	ID	O	Panel ID

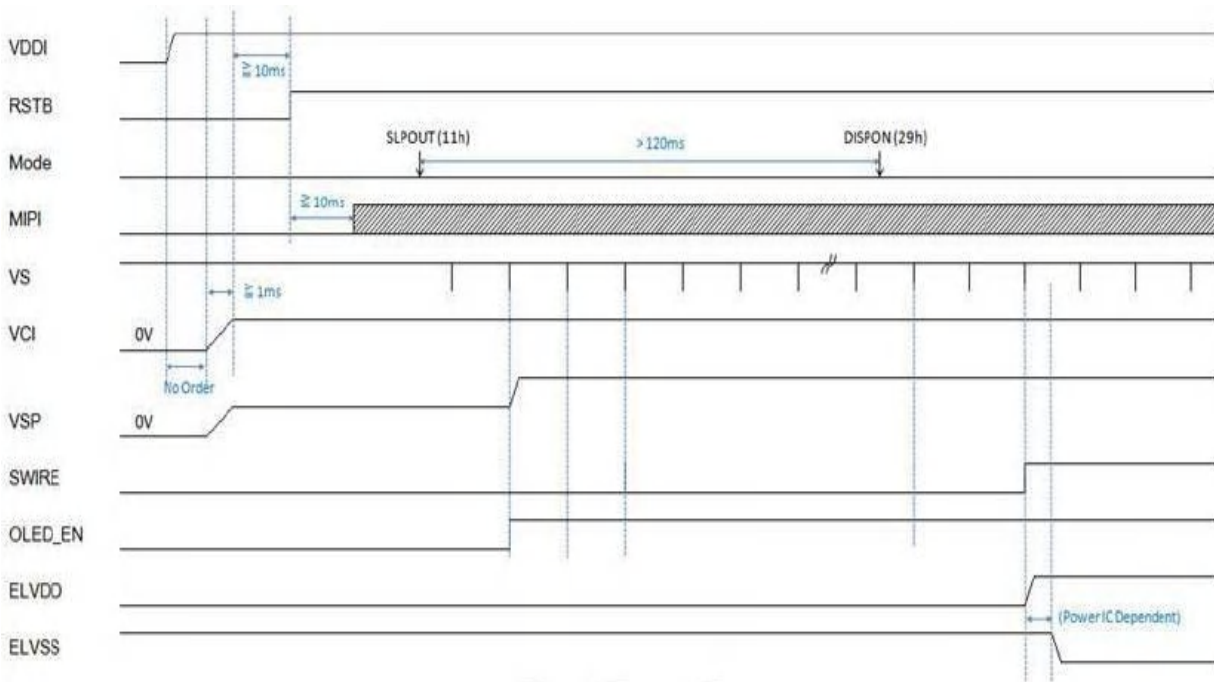
### 5.2.2 Display Module Block Diagram

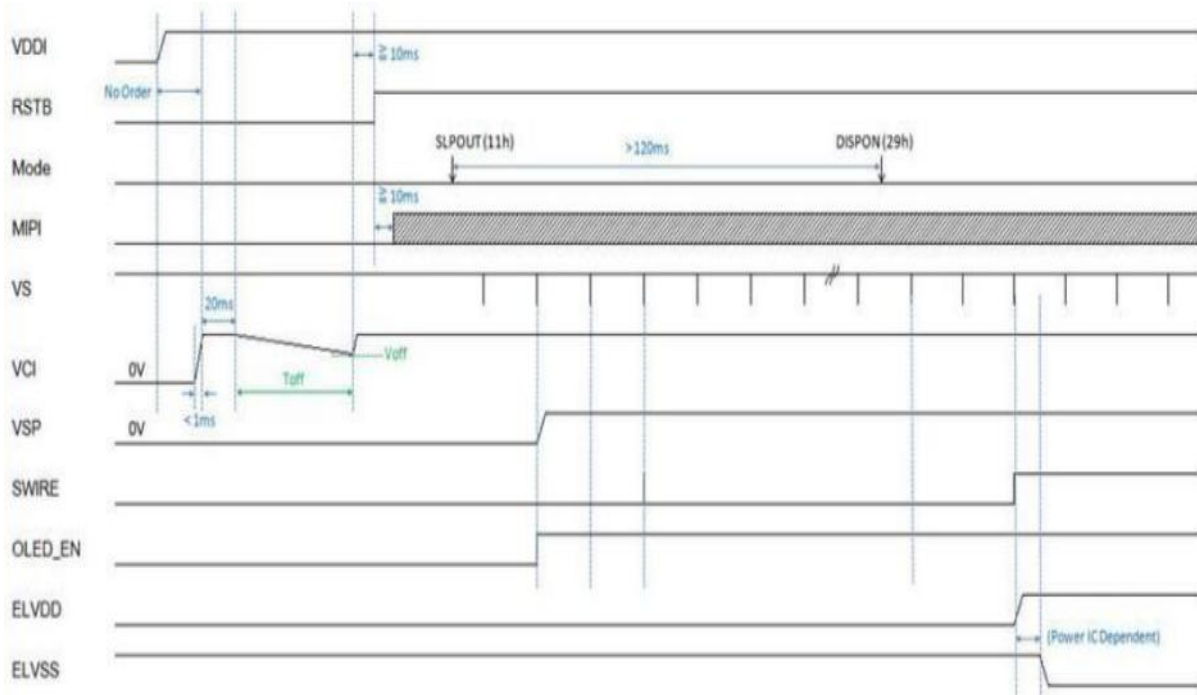


### 5.3 Recommended Operating Sequence

#### 5.3.1 Power on sequence

1. Power ON for Normal VCI Case:  $T_r > 1ms$



2. Power ON for fast VCI Case:  $T_r < 1\text{ms}$ 

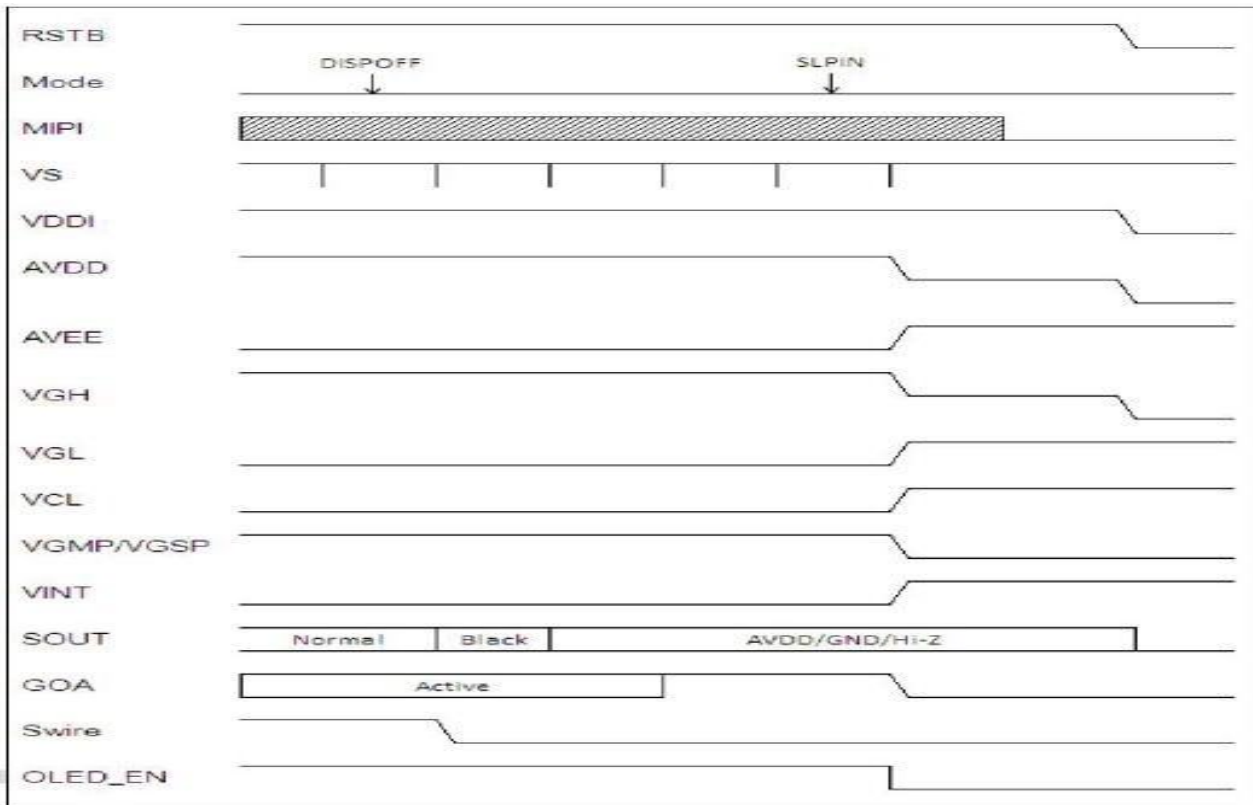
Note: If VCI's rising time is smaller than 1ms, it is suggested to use VCI H-L-H sequence to avoid the start-up issue due to fast VCI ramp up.

--the 1<sup>st</sup> H is suggested to be 20ms

--the L period is the time that can make Voff in between 2.6V and 1.5V.

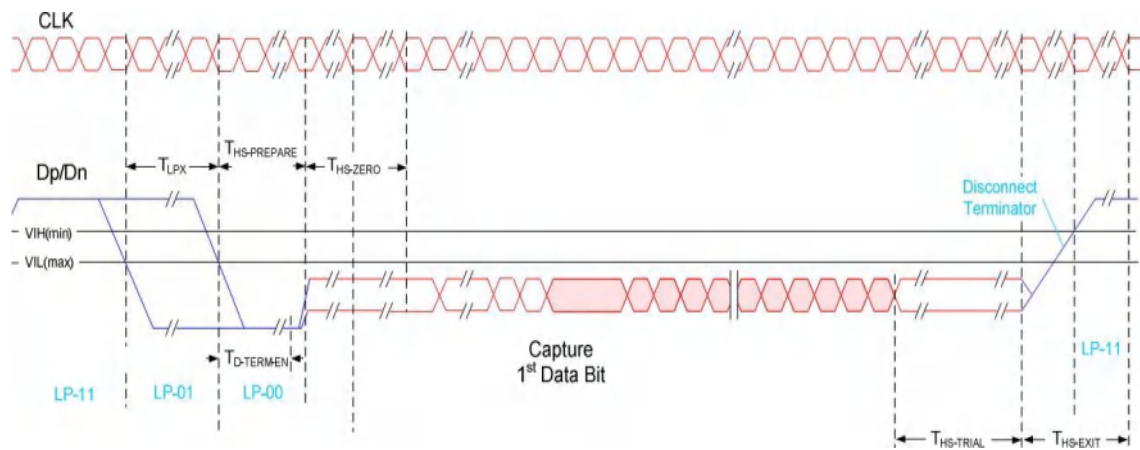
(for example, when the discharge time is 20ms and 200ms for VCI to drop below 2.6V and 1.5V, respectively. Then the Toff is suggested to be >20ms and <200ms.)

### 5.3.2 Power off sequence

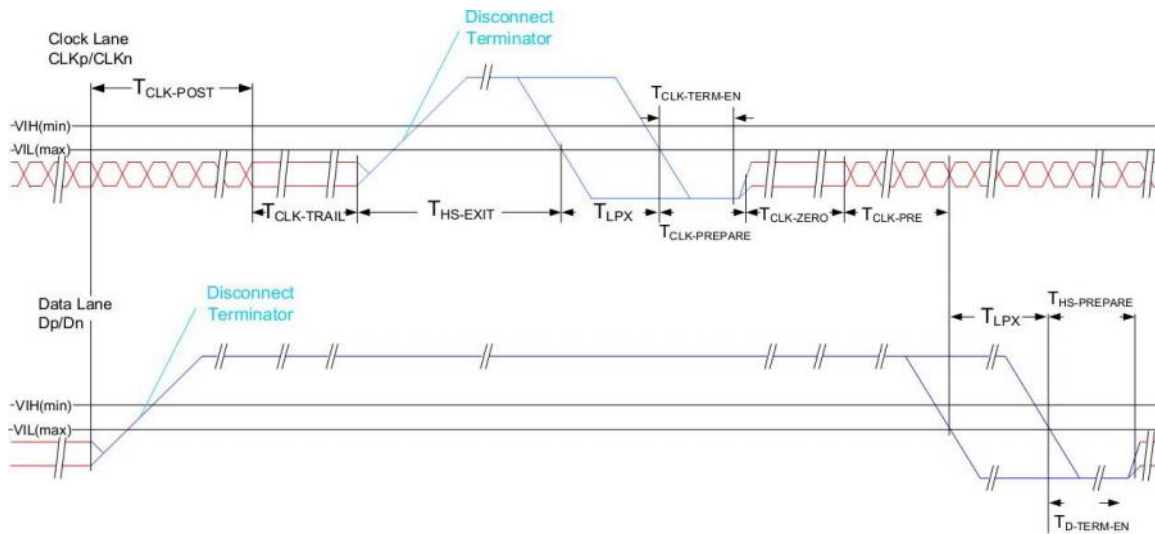


## 5.4 AC Characteristics ( MIPI )

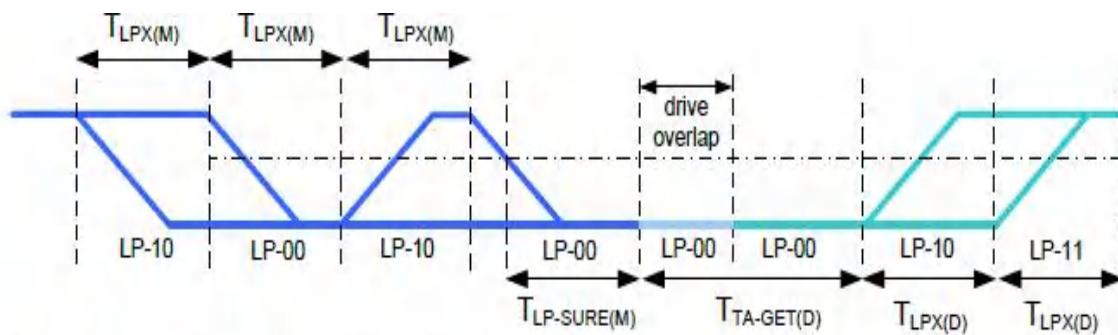
### 5.4.1 HS Data Transmission Burst



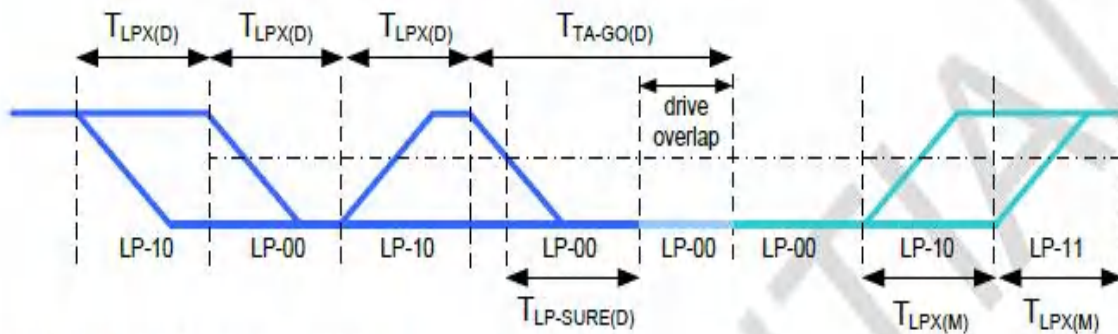
### 5.4.2 HS Clock Transmission



### 5.4.3 Turnaround Procedure



Bus turnaround (BAT) from MPU to display module timing



Bus turnaround (BAT) from display module to MPU timing

## 5.4.4 Timing Parameters

Timing Parameters:

Parameter	Description	Min	Typ	Max	Unit
$T_{\text{CLK-POST}}$	Time that the transmitter continues to send HS clock after the last associated Data Lane has transitioned to LP Mode. Interval is defined as the period from the end of $T_{\text{HS-TRAIL}}$ to the beginning of $T_{\text{CLK-TRAIL}}$ .	$60\text{ns} + 52*UI$			ns
$T_{\text{CLK-TRAIL}}$	Time that the transmitter drives the HS-0 state after the last payload clock bit of a HS transmission burst.	60			ns
$T_{\text{HS-EXIT}}$	Time that the transmitter drives LP-11 following a HS burst.	300			ns
$T_{\text{CLK-TERM-EN}}$	Time for the Clock Lane receiver to enable the HS line termination, starting from the time point when Dn crosses $V_{\text{IL,MAX}}$ .	Time for Dn to reach $V_{\text{TERM-EN}}$		38	ns
$T_{\text{CLK-PREPARE}}$	Time that the transmitter drives the Clock Lane LP-00 Line state immediately before the HS-0 Line state starting the HS transmission.	38		95	ns
$T_{\text{CLK-PRE}}$	Time that the HS clock shall be driven by the transmitter prior to any associated Data Lane beginning the transition from LP to HS mode.	8			UI
$T_{\text{CLK-PREPARE}} + T_{\text{CLK-ZERO}}$	$T_{\text{CLK-PREPARE}}$ + time that the transmitter drives the HS-0 state prior to starting the Clock.	300			ns
$T_{\text{D-TERM-EN}}$	Time for the Data Lane receiver to enable the HS line termination, starting from the time point when Dn crosses $V_{\text{IL,MAX}}$ .	Time for Dn to reach $V_{\text{TERM-EN}}$		$35\text{ ns} + 4*UI$	
$T_{\text{HS-PREPARE}}$	Time that the transmitter drives the Data Lane LP-00 Line state immediately before the HS-0 Line state starting the HS transmission	$40\text{ns} + 4*UI$		$85\text{ ns} + 6*UI$	ns
$T_{\text{HS-PREPARE}} + T_{\text{HS-ZERO}}$	$T_{\text{HS-PREPARE}}$ + time that the transmitter drives the HS-0 state prior to transmitting the Sync sequence.	$145\text{ns} + 10*UI$			ns
$T_{\text{HS-TRAIL}}$	Time that the transmitter drives the flipped differential state after last payload data bit of a HS transmission burst	$60\text{ns} + 4*UI$			ns

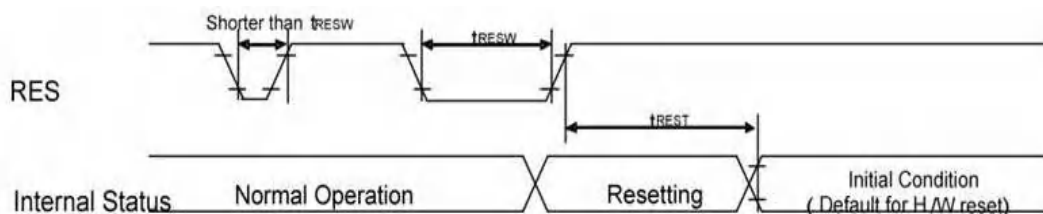
## Low Power Mode :

Parameter	Description	Min	Typ	Max	Unit	Notes
$T_{LPX(M)}$	Transmitted length of any Low-Power state period of MCU to display module	50		150	ns	1,2
$T_{TA-SURE(M)}$	Time that the display module waits after the LP-10 state before transmitting the Bridge state (LP-00) during a Link Turnaround.	$T_{LPX(M)}$		$2 * T_{LPX(M)}$	ns	2
$T_{LPX(D)}$	Transmitted length of any Low-Power state period of display module to MCU	50		150	ns	1,2
$T_{TA-GET(D)}$	Time that the display module drives the Bridge state (LP-00) after accepting control during a Link Turnaround.		$5 * T_{LPX(D)}$		ns	2
$T_{TA-GO(D)}$	Time that the display module drives the Bridge state (LP-00) before releasing control during a Link Turnaround.		$4 * T_{LPX(D)}$		ns	2
$T_{TA-SURE(D)}$	Time that the MPU waits after the LP-10 state before transmitting the Bridge state (LP-00) during a Link Turnaround.	$T_{LPX(D)}$		$2 * T_{LPX(D)}$	ns	2

## NOTE:

1.  $T_{LPX}$  is an internal state machine timing reference. Externally measured values may differ slightly from the specified values due to asymmetrical rise and fall times.
2. Transmitter-specific parameter

## 5.4.5 Timing requirements for RESETB



## Reset input timing:

IOVCC=1.65 to 3.6V, VDD=2.5 to 3.6V, AGND=DGND=0V, Ta=-40 to 85°C

Symbol	Parameter	Related Pins	MIN	TYP	MAX	Note	Unit
$t_{RESW}$	*1) Reset low pulse width	RESX	10	-	-	-	$\mu$ s
$t_{REST}$	*2) Reset complete time	-	-	-	5	When reset applied during Sleep in mode	ms
		-	-	-	120	When reset applied during Sleep out mode	ms

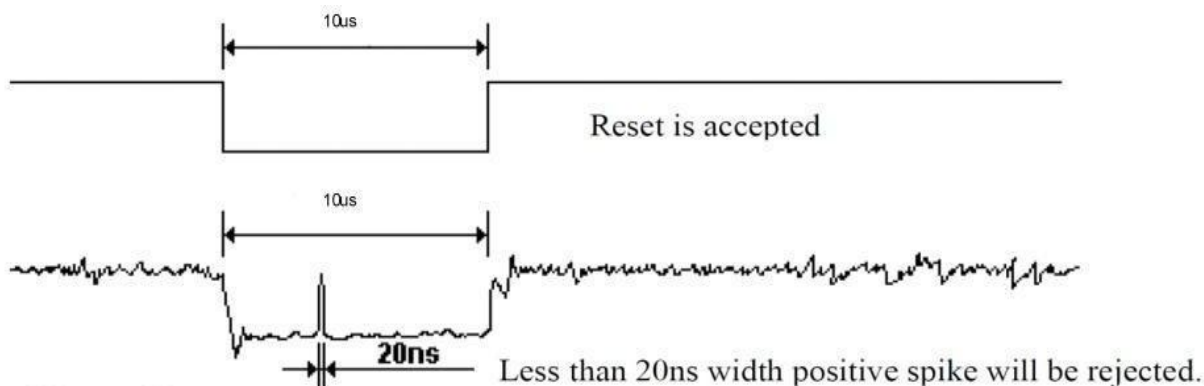
Note 1) Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below.

RESX Pulse	Action
Shorter than 5 $\mu$ s	Reset Rejected
Longer than 10 $\mu$ s	Reset
Between 5 $\mu$ s and 10 $\mu$ s	Reset starts (It depends on voltage and temperature condition.)

Note 2. During the resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In –mode) and then return to Default condition for H/W reset.

Note 3. During Reset Complete Time, data in OTP will be latched to internal register during this period. This loading is done every time when there is H/W reset complete time (tREST) within 5ms after a rising edge of RESX.

Note 4. Spike Rejection also applies during a valid reset pulse as shown below:



Note 5. It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.

## 6 Electro-Optical Specification

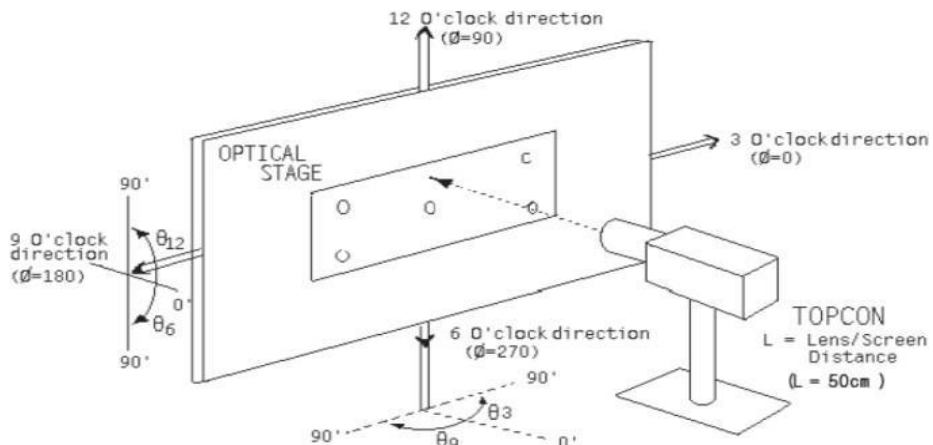
Item	Symbol	Conditions	Min.	Typ.	Max.	Unit	Remark	
Brightness		L255	315	350	385	cd/m <sup>2</sup>	Note1	
Brightness Uniformity		L255	75		-	%	Note2	
Contrast Ratio	CR	Normal to surface	60,000		-	-	Note3	
CIE Chromaticity	White	x	Normal to surface	0.275	0.295	0.315	-	
		y		0.285	0.305	0.325	-	
	Red	x		0.66	0.69	0.72	-	
		y		0.28	0.31	0.34	-	
	Green	x		0.195	0.235	0.275	-	
		y		0.68	0.72	0.76	-	
	Blue	x		0.113	0.143	0.173	-	
		y		0.014	0.044	0.074	-	
Color Gamut		vs. NTSC	90	105		%		
Viewing angle		U/D/L/R CR≥1000	80		-	°		
Color shift (JNCD)		@ 45 degree			6		Note4	
Cross-talk			-	-	2	%	Note5	
Gamma		V(Gray)= 48,72,104,132,164, 192,224,255	2.0	2.2	2.4	-		
Response time			-	-	2	ms	Note6	
Flicker		Normal $\Theta = \Phi = 0^\circ$			-40	dB	Note 7	
Image Retention					3	min	Note 8	
Image Sticking					3	hrs	Note 9	
Color Uniformity		Full White $\Delta u'v'$			0.012		Note 10	

※亮度均匀度以 L255 进行测量。

※Mura 检测在 L128 状态进行判别

**Note1: Temp.25°C, (Angle、 distance)**

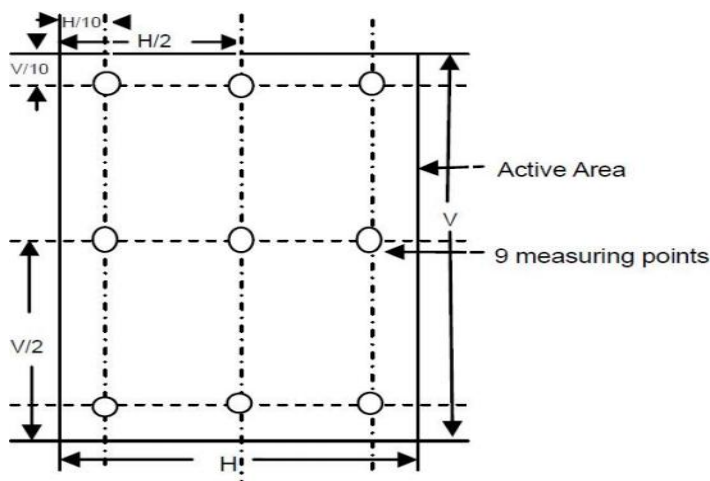
Environmental conditions: Temp.25°C±3°C, 65±20%RH, Dark Room 。  
 Distance of OLED display center to measuring machine is 50cm.



**Note2: Brightness Uniformity definition**

Measure 9 points of Display Brightness,

$$\text{Luminance uniformity} = \frac{(\text{Min Luminance of 9 points})}{(\text{Max Luminance of 9 points})} \times 100\%$$



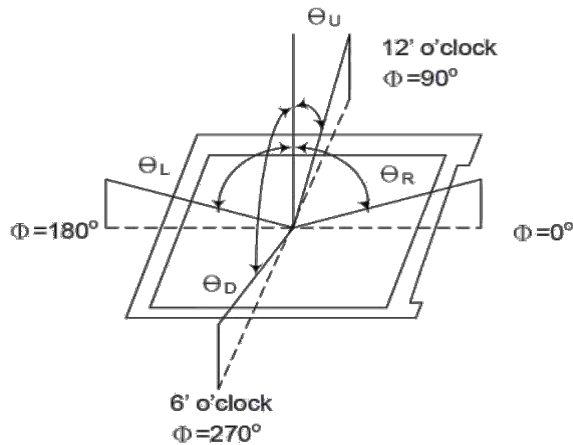
**Note3: Contrast Ratio**

Dark Room C.R=LW/LB

LW: full white brightness of display center P0;

LB : full black brightness of display center P0.

Contrast Ratio Uniformity = CRmin / CRmax



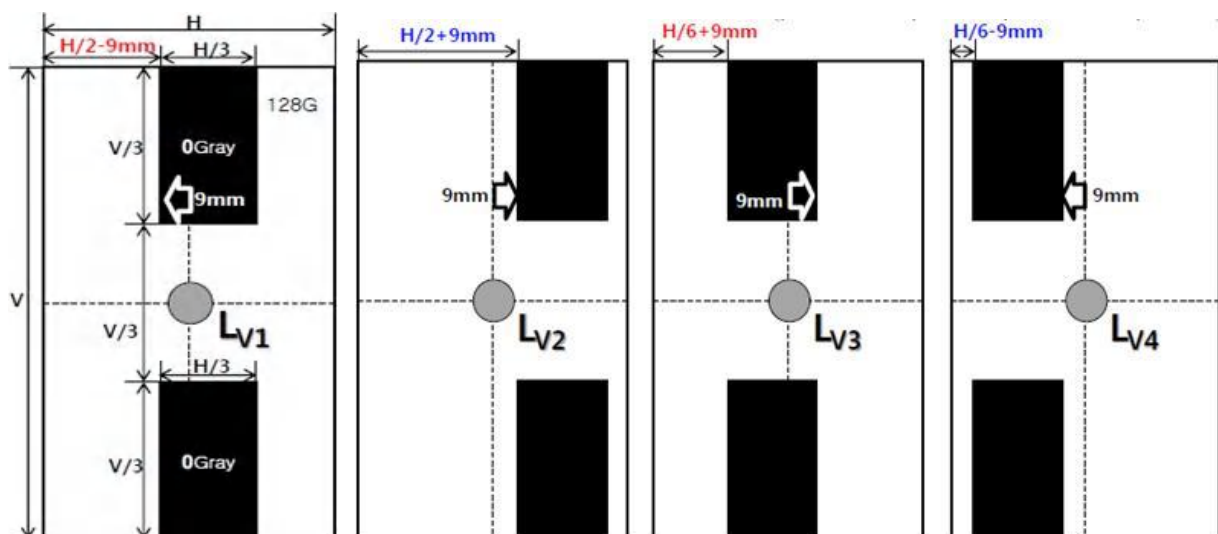
**Note4: Color Shift JNCD**

- For JNCD measure:
- Fix on the white pattern,
- On the condition  $\theta=0$   $F=0^\circ$ , we can get the color coordinate  $(u_1', v_1')$  and on  $\theta F=45^\circ$  we can get another color coordinate  $(u_2', v_2')$
- $\Delta = \text{Square Root}((u_2'-u_1')^2 + (v_2'-v_1')^2)$
- JNCD stands for "Just Noticeable Color Difference"
- For the  $(u', v')$  color space  $\text{JNCD}=0.0040$ .
- 4 JNCD means  $\Delta u'v' < 0.016$

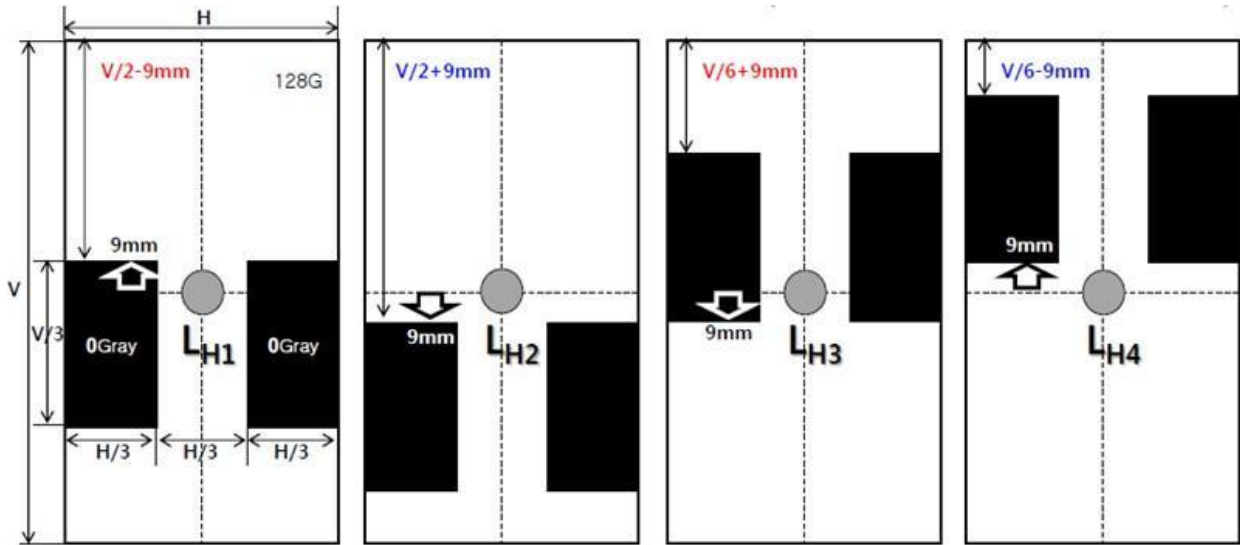
**Note5: Cross-talk**

22% black window , 128 gray background. Pattern Left/Right 9mm shift

$$\text{Crosstalk}(V) = \max\left(\left|\frac{L_{V1} - L_{V2}}{L_{V2}}\right| \times 100, \left|\frac{L_{V3} - L_{V4}}{L_{V4}}\right| \times 100\right)$$



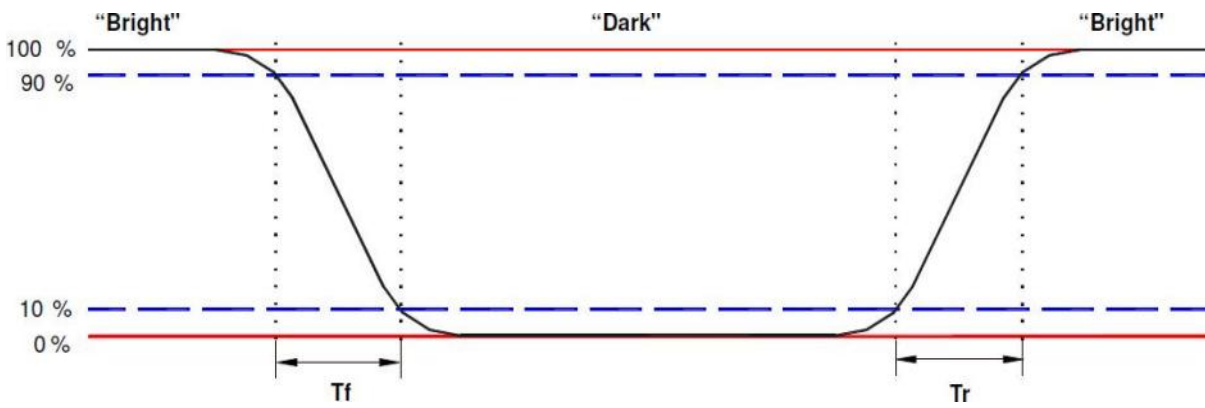
$$Crosstalk(H) = \max\left(\left|\frac{L_{H1} - L_{H2}}{L_{H2}}\right| \times 100, \left|\frac{L_{H3} - L_{H4}}{L_{H4}}\right| \times 100\right)$$



**Note6: Response Time**

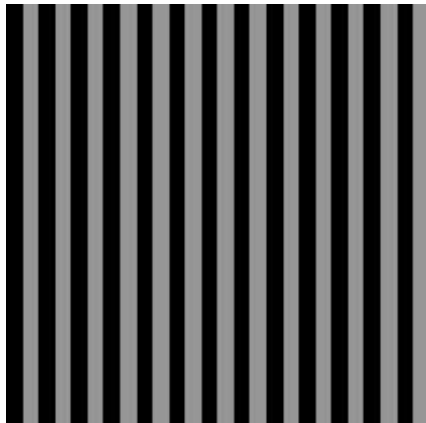
Response time=Pixel turn on and turn off time (White<=>Black).

It is measuring transition time from 10% to 90% of luminance.



**Note 7: Flicker**

Suggested Instruments: Konica Minolta CA-310 or Klein Instruments K-8



**Odd row : L0 Black**  
**Even row : L186 gray level**

**Flicker Test Pattern**

The flicker level is defined by **Fast Fourier Transformation (FTT)** as follows:

$$Flicker = 20 \log_{10} \left( 2 \frac{f_{FFTc}(n)}{f_{FFTc}(0)} \right) + FS(Hz) \quad (dB)$$

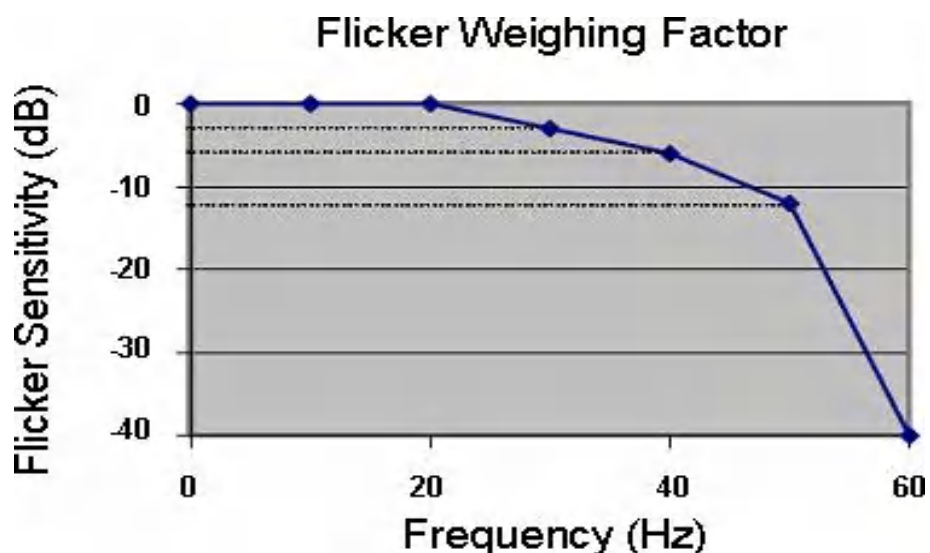
Where

$f_{FFTc}(n)$  is the n-th FFT coefficient.

$f_{FFTc}(0)$  is the 0-th FFT coefficient which is DC component.

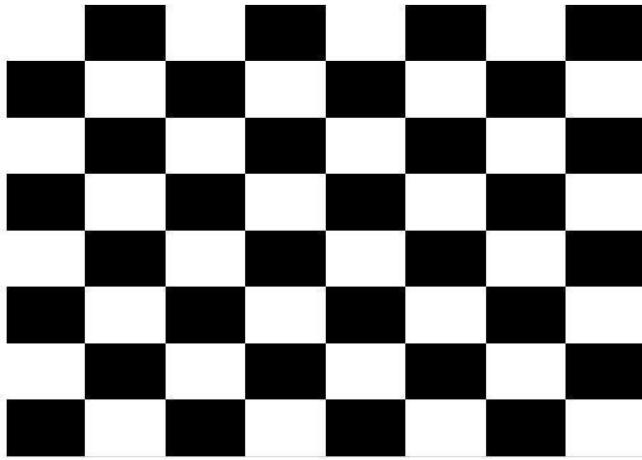
**FS(Hz)** is the flicker sensitivity as a function of frequency.

The peak flicker level shall be reported based on the calculation using above formula in which FS(Hz) is determined by the flicker weighing factor shown below.



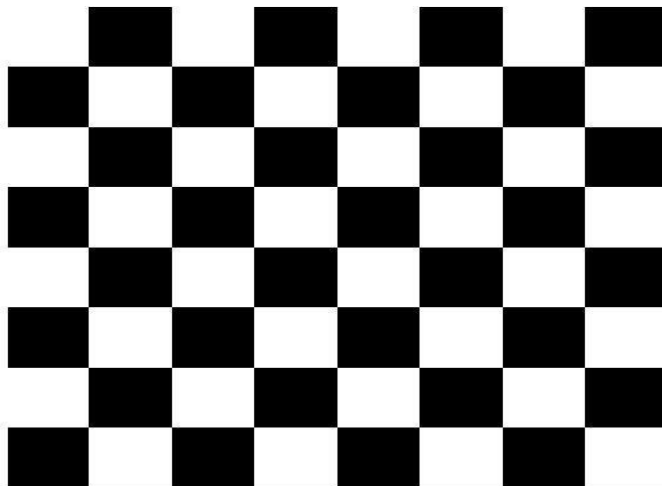
**Note8: Image Retention**

Using chessboard pattern (8 \* 8) light on 1hr, and switch to 127 gray. The Image retention should not be seen after 3 mins.

**Note9: Image Sticking**

Using chessboard pattern (8 \* 8) light on 3 hrs, and switch to 127 gray.

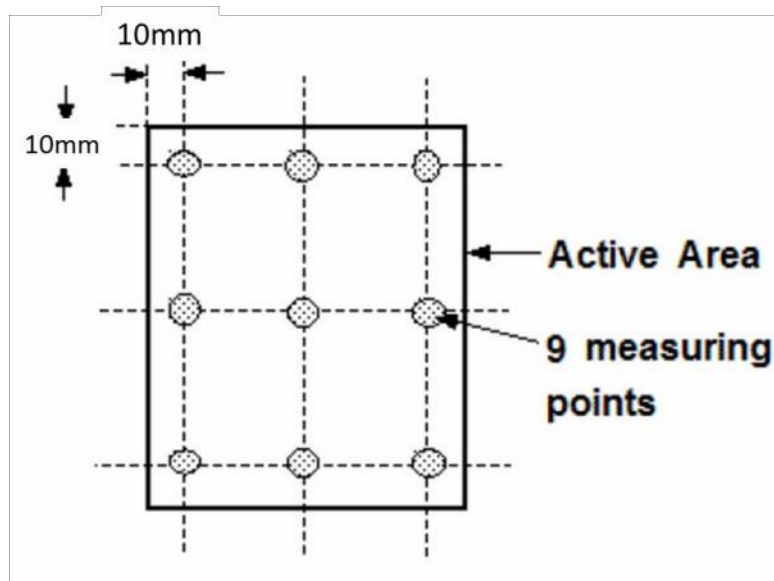
The Image Sticking should not be seen after 60 min with ND02 filter (image sticking disappear after stewing).



**Note10: Color Uniformity**

Total 9 measure points should set as shown in the following figures. The CIE 1967 Standards shall be used. The color difference is calculated by using following formula:

Max ( $\Delta u'v'$ ) (the max  $\Delta u'v'$  value between two random point of 9 point)

**7 Reliability****7.1 Environmental Test**

No	Item	Conditions	Quantity	Note
1	High Temperature Operating (HTO)	70°C/48hrs	5pcs	After testing - No clearly visible defects or remarkable deterioration of display quality. However, any polarizer's deteriorations by the high temperature/ High humidity test are permitted. - No function-related abnormalities.
2	Low Temperature Operating (LTO)	-20°C/48hrs	5pcs	
3	High Temperature Storage (HTS)	80°C/48hrs	5pcs	
4	Low Temperature Storage (LTS)	-40°C/48hrs	5pcs	
5	High Temperature / High Humidity Operating (HTHHO)	60°C /93%R.H./96hrs	5pcs	
6	High Temperature/High Humidity Storage (HTHHS)	60°C /93%R.H./96hrs	5pcs	

## 7.2 Electrical Test

No	Item	Conditions	Note
1	Air discharged Criteria C	$\pm 8kV$	After testing - Hard defect should not happen. - If it would be recovered to normal state after resetting, it would be judged as a good state. ( Class C )
2	Contact discharged Criteria C	$\pm 4kV$	

## 7.3 Mechanical Test

No	Item	Conditions	Note
1	Glass Strength Test	4PB, B10 >100MPa (stress)	
2	Ball Drop Test	0.2J @ center 32g, 45cm 屏幕中心 3 次, 四个角各 1 次	Module with CG
3	Drop Test	10 Drops: 6 surfaces / 3 edges / 1 corner / for Carton test & Gift Box Test 0~9kg / 92cm 9.2kg~18.2kg / 76cm 18.3kg~27.2kg / 61cm 27.3kg~45.4kg / 46cm	Package
4	Vibration Test	Accleration: 1.48Grms 5~100Hz 0.015G*2/Hz/ 100~200Hz -6dB/Oct/ 200Hz 0.0038G*2/Hz/ Test Time : 30 min	Package

## 8 Handling Precautions

- 8.1 When cleaning ITO pad, avoid using hard and abrasive material or corrosive solution
- 8.2 Keep module away from direct sunlight or fluorescent light, and keep it at room temperature and humidity
- 8.3 Strong impact & pressure on module and packing is prohibited
- 8.4 Following normal power on/off sequence is necessary for preventing abnormal display or permanent damage to display
- 8.5 Optimal contrast ratio under ideal voltage is AMOLED module's characteristic, hence it is recommended a voltage control function available
- 8.6 Image sticking may occur if an image displays for an extended period of time
- 8.7 When interfered by system's overall mechanical design, an abnormal display may occur
- 8.8 After considering emitting energy, you should plan your design to satisfy EMI standards.
- 8.9 Host side should place a surge-prevent circuit at power trace (ie: VCI, Vddi) to protect AMOLED module.

# 9 Outline Dimension Drawing

由 Autodesk 教育版产品制作

**技术要求:**

- 玻璃显示模式: AMOLED 5.44" FHD  
视角: All  
分辨率: 1080 (RGB) X1920 DOTS  
驱动芯片型号: RM67199  
玻璃型号: 和辉光电  
未注尺寸公差及装配公差: ±0.2mm  
② 带 $\phi$ 为重量尺寸  
③ 材料及工艺要求符合RoHS  
④ 建设模组背面机壳在厚度方向预留0.3mm间隙  
⑤ 建设VIL前置比槽距A单边大0.3mm间隙

**正视图**

0.2mm厚泡  
补胶抓手

折弯示意图  
产品展开出货

**技术规格:**

接口模式	MIP1 V1D80 模式
工作电压	VCC: 2.8V 10VCC: 1.8V
平均亮度	350cd/m <sup>2</sup> (typ), 315/ cd (min)
中心点包度	色度XY以密封为中心值±0.03;
背光电源参数	
连接器	WPT5-S040VA1
工作温度	-20° C TO 60° C
储存温度	-30° C TO 70° C

**模组图纸**

项目型号	5.5_FHD_AMOLED显示屏		
单位	mm	比例	1:1
第三版角	表		

**图纸名称**

设计 检查 批准 其他

日期 2020.08.26

签名

**图例:**

- 玻璃
- 封装胶
- 导电胶
- 导电区
- 封装胶
- 封装胶

显示模组单体

**尺寸表:**

No.	Pin Left/Fe	No.	Pin Left/Fe
1	DM6	21	DM8
2	DM2	22	DM
3	DM3	23	DM
4	VDM11	24	DM9
5	VDM2	25	DM
6	VDM13	26	DM
7	VDM14	27	DM0
8	VDM15	28	DM3
9	DM4	29	VDM0
10	VDM	30	VDM
11	DM1	31	DM
12	DM5	32	DM0
13	DM9	33	DM0, DM2, DM3
14	DM	34	DM, DM1, DM7
15	DM5	35	DM, DM4
16	DM	36	DM, DM
17	DM	37	DM, DM1
18	DM7	38	DM, DM1
19	DM	39	DM
20	DM	40	DM

## 10 Packing Specification